

Introduction

As per [XCN05018](#) (released on December 12, 2005), device families available in the Chip Scale (package code CS) and lead-free Chip Scale (package code CSG) will be manufactured with a laminate substrate at Amkor Philippines beginning in December 2005.

Qualification Data

Following is the qualification data for laminate substrate packages manufactured at Amkor Philippines:

Table 1: Qualification Data for Laminate CSG144 Package

Product	Package	Rel#	Purpose	Stress	Started	Pre-Con	500 hrs	1000 hrs
XCV200E	CSG144	032105TC	Qualification of Laminate CSG144 Package	TCB MSL 3, 260C	10/3/05	0/76	0/76	0/76
		032205TH		TH MSL 3, 260C	10/3/05	0/77	0/77	0/77
		032305HTS		HTS 150C	10/3/05		0/77	0/77

Revision History

Date	Version	Revision
12/12/05	1.0	Initial Xilinx Release